

**AMENDMENT TO THE SPECIFICATION**

**Please amend the paragraph beginning on page 3, line 10 as follows:**

Next, as shown in Fig. 5F, remove selectively copper foils from given places on the ~~surfacee~~ surface of copper-clad laminated board 57 by etching, and form circuit patterns 58, thereby completing board 59.

**Please amend the paragraph beginning on page 6, line 27 as follows:**

Another method of manufacturing boards of the present invention comprises:

- laminating a prepreg on a metal foil;
- heating and pressing the prepreg at given places for fixing the prepreg to the metal foil;
- laminating a board, which includes a circuit pattern, on the prepreg;
- heating and pressing the board at given places for fixing the board to the prepreg;
- laminating another prepreg on the board;
- heating and pressing the another prepreg at ~~[[give]]~~ given places for fixing the another prepreg to the board;
- laminating another metal foil thereon;
- heating and pressing the another metal foil at ~~[[give]]~~ given places for fixing the another metal foil to the another prepreg; and
- heating and pressing the foregoing entire pressed and heated unit.--